L Number	Hits	Search Text	DB	Time stamp
1	24006	(semiconductor near1 (device package packaging)) and (leadframe (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/21 07:43
2	4583	(flat near1 package) qfp	USPAT; EPO; JPO	2003/04/21 07:25
3	3519	flat near1 package	USPAT; EPO; JPO	2003/04/21 07:25
4	2456	(flat near1 package) and (method process)	USPAT; EPO; JPO	2003/04/21 07:26
5	1497	((flat near1 package) and (method process)) and (chip die)	USPAT; EPO; JPO	2003/04/21 07:42
6	989	(((flat near1 package) and (method process)) and (chip die)) and (sealing sealed encapsulant encapsulating encapsulated)	USPAT; EPO; JPO	2003/04/21 07:43
7	508	((((flat near1 package) and (method process)) and (chip die)) and (sealing sealed encapsulant encapsulating encapsulated)) and (leadframe (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/21 07:46
8	237	(((((flat near1 package) and (method process)) and (chip die)) and (sealing sealed encapsulant encapsulating encapsulated)) and (leadframe (lead adj frame))) and (bump ball)	USPAT; EPO; JPO	2003/04/21 07:48
27	2	("6031292" | "6215179").PN.	USPAT	2003/04/21 08:01
28	9	6031292.URPN.	USPAT	2003/04/21 08:03
31	2	("5371407" | ."5625222").PN.	USPAT	2003/04/21 08:04